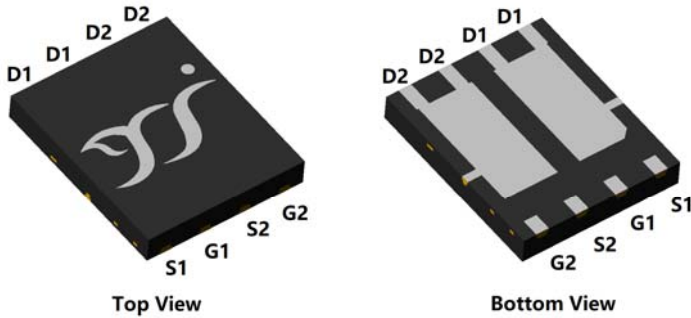
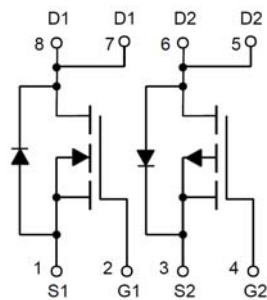


## N-Channel and P-Channel Complementary MOSFET



DFN5060-8L



### Product Summary

#### NMOS

• $V_{DS}$	100V
• $I_D$	25A
• $R_{DS(ON)}$ ( at $V_{GS}=10V$ )	<26m $\Omega$
• $R_{DS(ON)}$ ( at $V_{GS}=6V$ )	<27m $\Omega$
• $R_{DS(ON)}$ ( at $V_{GS}=4.5V$ )	<30m $\Omega$

#### PMOS

• $V_{DS}$	-100V
• $I_D$	-12A
• $R_{DS(ON)}$ ( at $V_{GS}=-10V$ )	<120m $\Omega$
• $R_{DS(ON)}$ ( at $V_{GS}=-6V$ )	<125m $\Omega$
• $R_{DS(ON)}$ ( at $V_{GS}=-4.5V$ )	<130m $\Omega$

### General Description

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- Moisture Sensitivity Level 3
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

### Applications

- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

### ■ Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	NMOS	PMOS	Unit
Drain-source Voltage		$V_{DS}$	100	-100	V
Gate-source Voltage		$V_{GS}$	$\pm 20$	$\pm 20$	V
Drain Current	$T_A=25^\circ\text{C}$	$I_D$	5	2.5	A
	$T_A=100^\circ\text{C}$		3	1.6	
	$T_C=25^\circ\text{C}$		25	-12	
	$T_C=100^\circ\text{C}$		15	-7	
Pulsed Drain Current <sup>A</sup>		$I_{DM}$	80	-40	A
Avalanche energy <sup>B</sup>		EAS	64	72	mJ
Total Power Dissipation <sup>C</sup>	$T_A=25^\circ\text{C}$	$P_D$	2	1.5	W
	$T_A=100^\circ\text{C}$		0.8	0.6	
	$T_C=25^\circ\text{C}$		62	42	
	$T_C=100^\circ\text{C}$		25	16	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+150	-55~+150	$^\circ\text{C}$



# YJG12NP10A

## ■ Thermal resistance

Parameter	Symbol	NMOS		PMOS		Units	
		Typ	Max	Typ	Max		
Thermal Resistance Junction-to-Ambient <sup>D</sup>	Steady-State	$R_{\theta JA}$	50	60	65	80	°C/W
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	1.5	2	2.5	3	

## ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJG12NP10A	F1	YJG12NP10A	5000	10000	100000	13" reel

## ■ NMOS Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=100V, V_{GS}=0V$	-	-	1	$\mu A$
		$V_{DS}=100V, V_{GS}=0V, T_J=150^\circ\text{C}$	-	-	100	
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2	1.7	2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=25A$	-	19	26	m $\Omega$
		$V_{GS}=6V, I_D=10A$	-	21	27	
		$V_{GS}=4.5V, I_D=5A$	-	22	30	
Diode Forward Voltage	$V_{SD}$	$I_S=25A, V_{GS}=0V$	-	0.9	1.3	V
Gate resistance	$R_G$	f=1MHz, Open drain	-	1.5	-	$\Omega$
Maximum Body-Diode Continuous Current	$I_S$		-	-	25	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=50V, V_{GS}=0V, f=1\text{MHz}$	-	1200	-	pF
Output Capacitance	$C_{oss}$		-	400	-	
Reverse Transfer Capacitance	$C_{rss}$		-	10	-	
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{GS}=10V, V_{DS}=50V, I_D=12.5A$	-	32	-	nC
Gate-Source Charge	$Q_{gs}$		-	11	-	
Gate-Drain Charge	$Q_{gd}$		-	5	-	
Reverse Recovery Charge	$Q_{rr}$	$I_F=12.5A, di/dt=100A/\mu s$	-	85	-	nC
Reverse Recovery Time	$t_{rr}$		-	52	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DD}=50V, I_D=12.5A$ $R_{GEN}=2.2\Omega$	-	50	-	ns
Turn-on Rise Time	$t_r$		-	15	-	
Turn-off Delay Time	$t_{D(off)}$		-	70	-	
Turn-off fall Time	$t_f$		-	20	-	



# YJG12NP10A

## ■ PMOS Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =-250μA	-100	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V	-	-	-1	μA
		V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V, T <sub>J</sub> =150°C	-	-	-100	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.2	-1.7	-2.5	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-12A	-	90	120	mΩ
		V <sub>GS</sub> =-6V, I <sub>D</sub> =-6A	-	93	125	
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A	-	98	130	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-12A, V <sub>GS</sub> =0V	-	-0.9	-1.2	V
Gate resistance	R <sub>G</sub>	f=1MHz, Open drain	-	10	-	Ω
Maximum Body-Diode Continuous Current	I <sub>S</sub>		-	-	-12	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-50V, V <sub>GS</sub> =0V, f=1MHz	-	1100	-	pF
Output Capacitance	C <sub>oss</sub>		-	110	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	10	-	
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-50V, I <sub>D</sub> =-6A	-	20	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	4	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	4.5	-	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =-6A, di/dt=100A/us	-	140	-	nC
Reverse Recovery Time	t <sub>rr</sub>		-	70	-	ns
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =-10V, V <sub>DD</sub> =-50V, I <sub>D</sub> =-6A RGEN=2.2Ω	-	10	-	ns
Turn-on Rise Time	t <sub>r</sub>		-	30	-	
Turn-off Delay Time	t <sub>D(off)</sub>		-	77	-	
Turn-off fall Time	t <sub>f</sub>		-	80	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B. NMOS: T<sub>J</sub>=25°C, V<sub>DD</sub>=50V, V<sub>G</sub>=10V, R<sub>G</sub>=25Ω, L=0.5mH, I<sub>AS</sub>=16A.  
PMOS: T<sub>J</sub>=25°C, V<sub>DD</sub>=-50V, V<sub>G</sub>=-10V, R<sub>G</sub>=25Ω, L=0.5mH, I<sub>AS</sub>=-17A.

C. P<sub>d</sub> is based on max. junction temperature, using junction-case thermal resistance.

D. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in the still air environment with T<sub>A</sub>=25°C.  
The maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.



# YJG12NP10A

## ■ NMOS Typical Electrical and Thermal Characteristics Diagrams

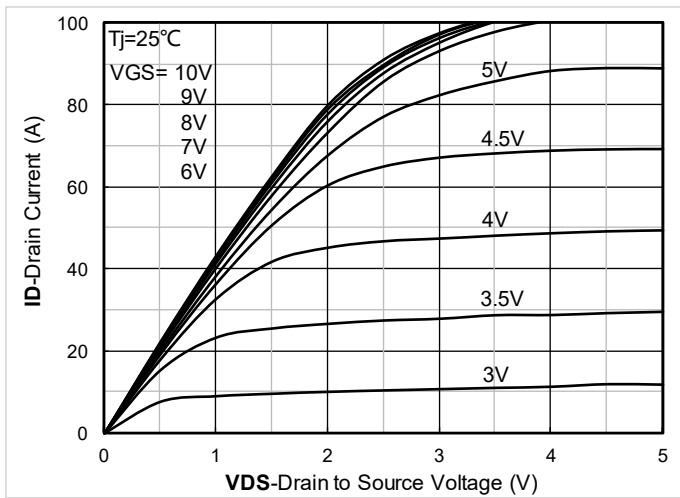


Figure 1. Output Characteristics

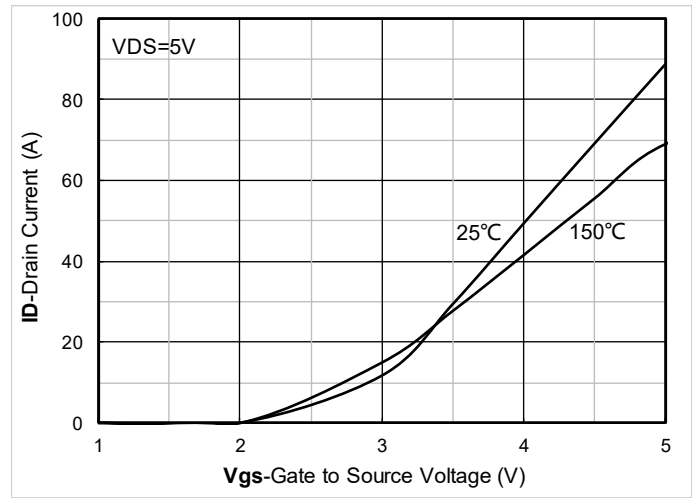


Figure 2. Transfer Characteristics

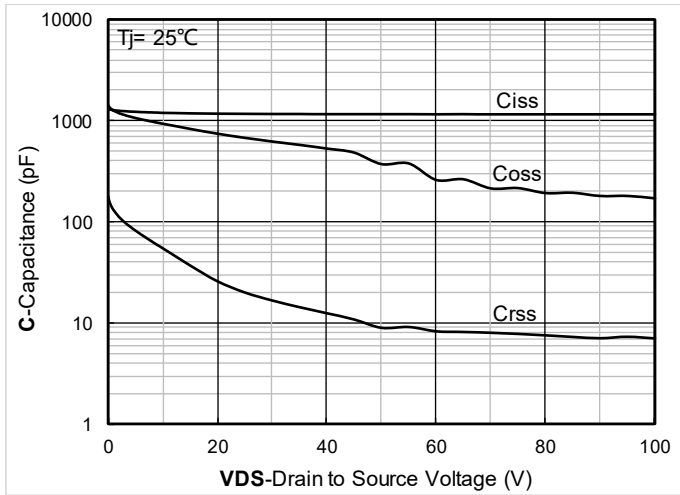


Figure 3. Capacitance Characteristics

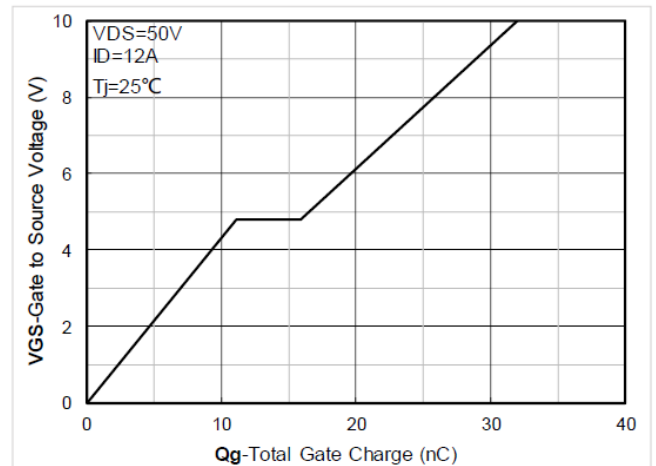


Figure 4. Gate Charge

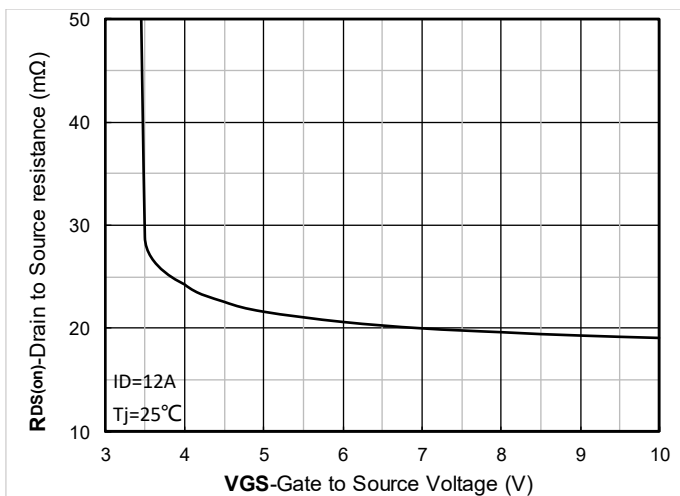


Figure 5. On-Resistance vs Gate to Source Voltage

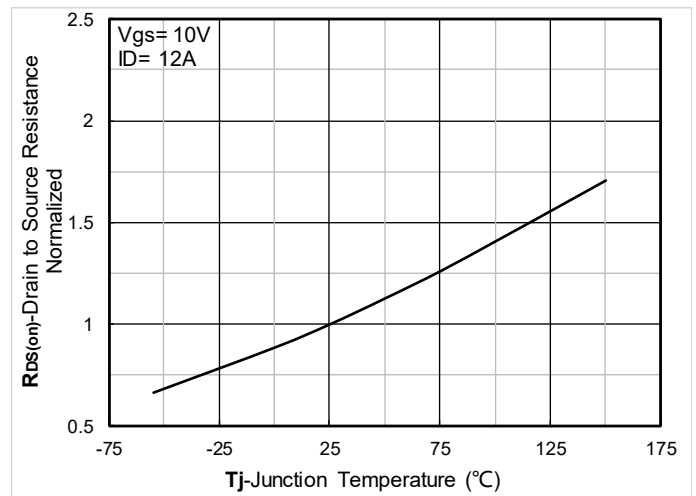


Figure 6. Normalized On-Resistance



# YJG12NP10A

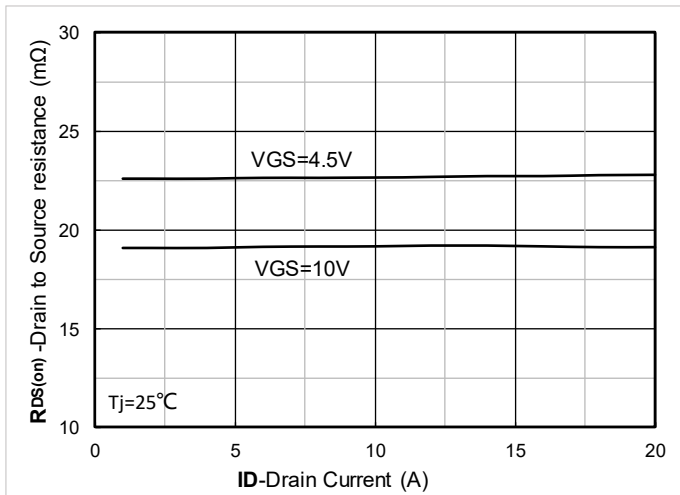


Figure 7. RDS(on) VS Drain Current

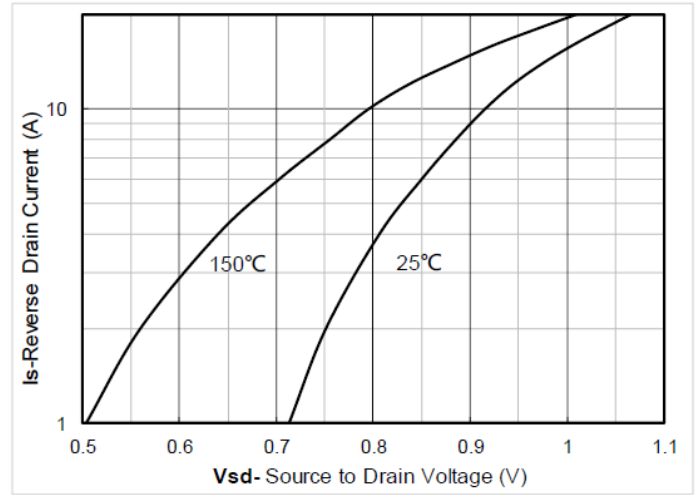


Figure 8. Forward characteristics of reverse diode

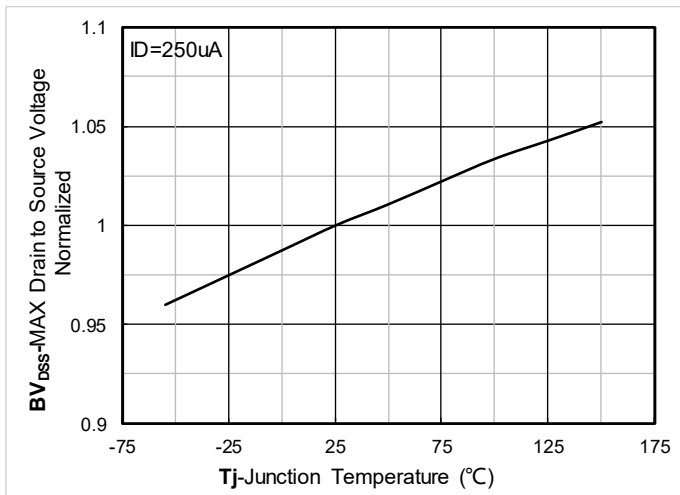


Figure 9. Normalized breakdown voltage

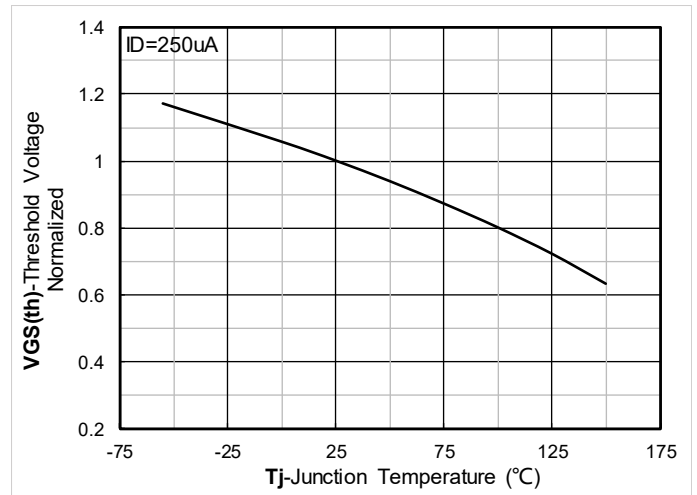


Figure 10. Normalized Threshold voltage

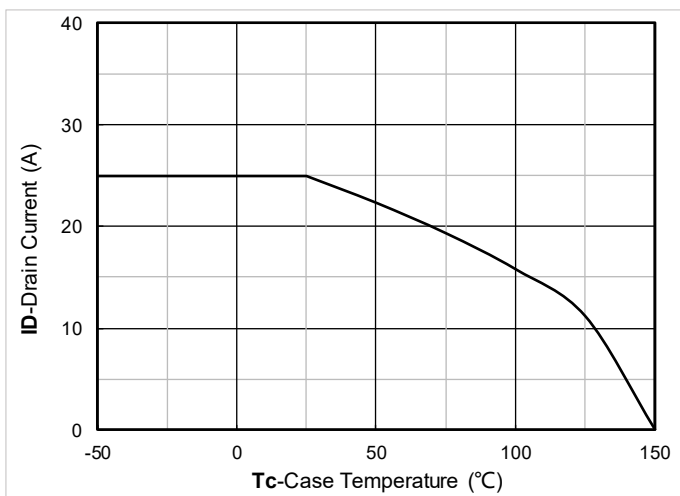


Figure 11. Current dissipation

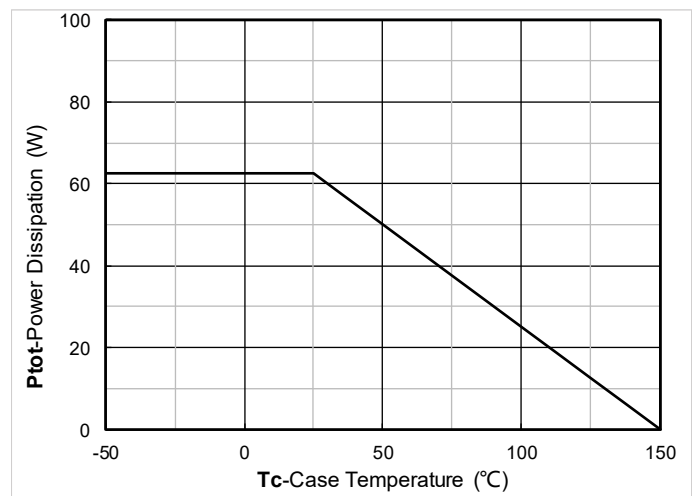


Figure 12. Power dissipation



# YJG12NP10A

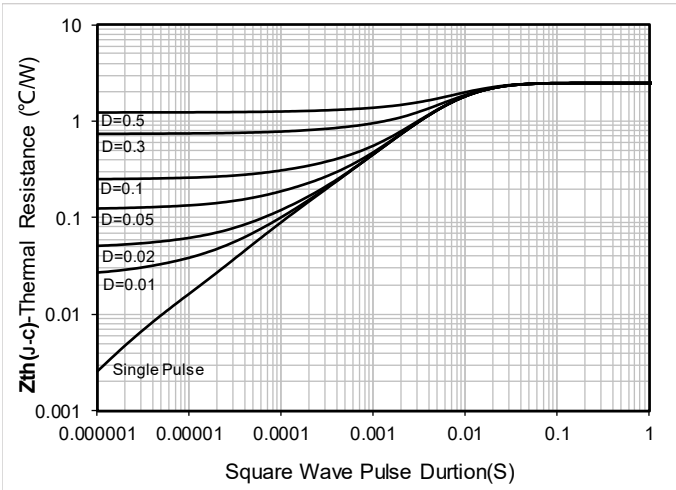


Figure 13. Maximum Transient Thermal Impedance

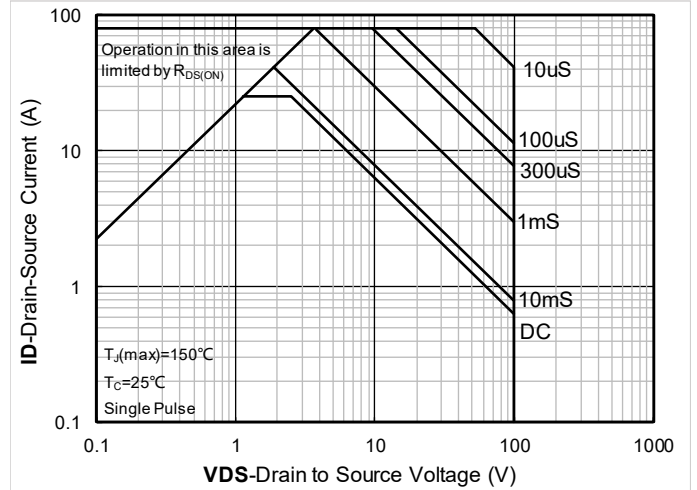


Figure 14. Safe Operation Area

## PMOS Typical Electrical and Thermal Characteristics Diagrams

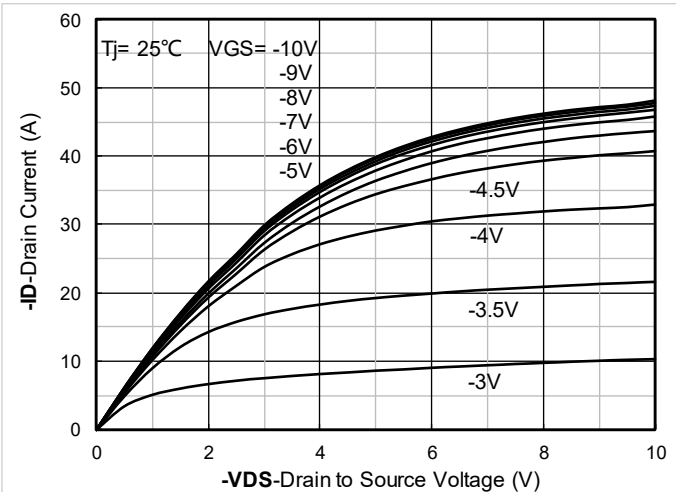


Figure 1. Output Characteristics

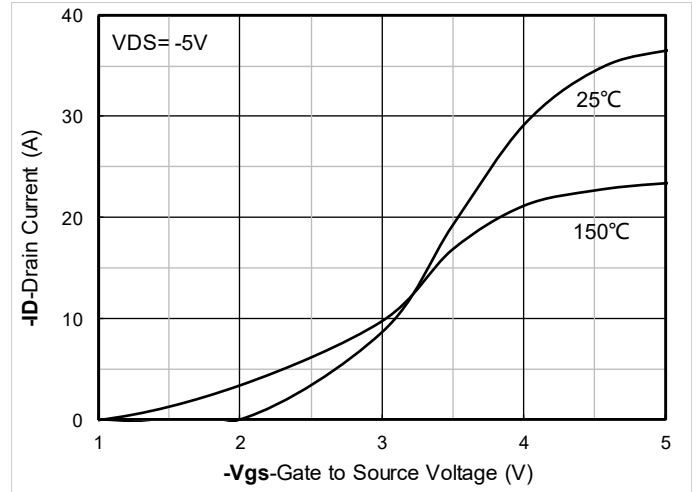


Figure 2. Transfer Characteristics

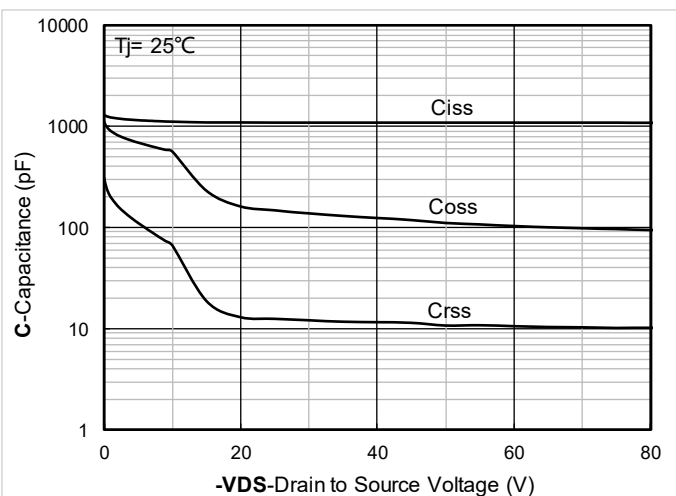


Figure 3. Capacitance Characteristics

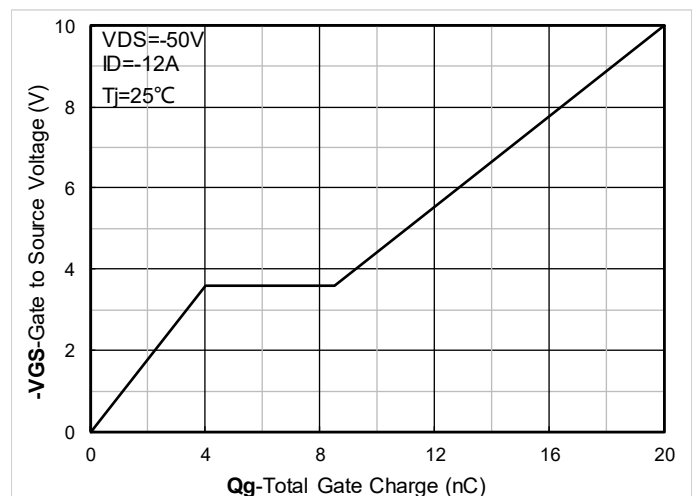


Figure 4. Gate Charge



# YJG12NP10A

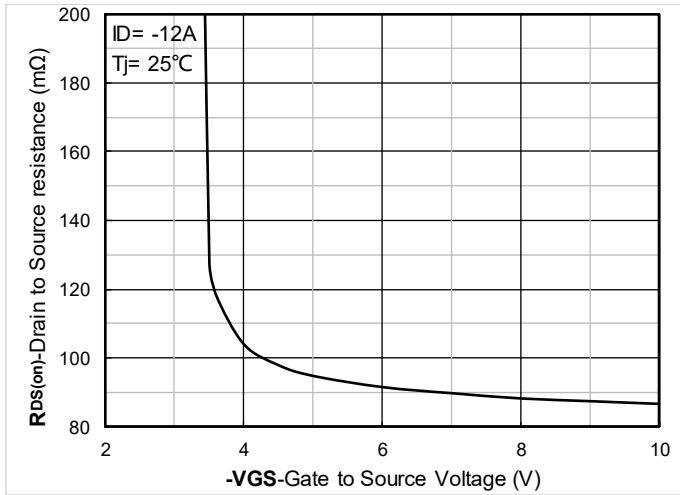


Figure 5. On-Resistance vs Gate to Source Voltage

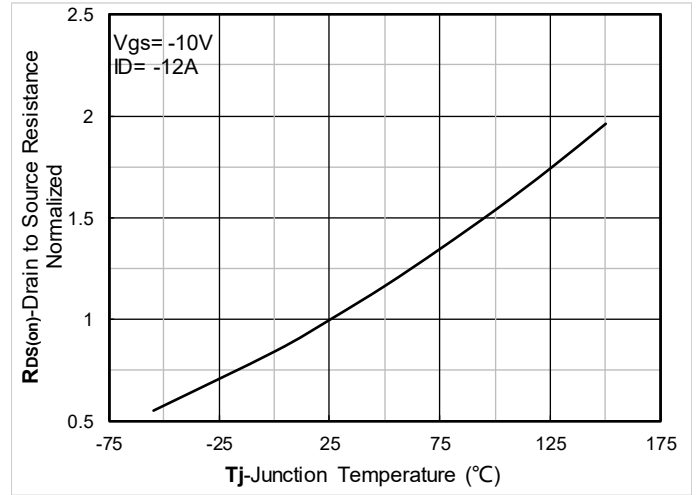


Figure 6. Normalized On-Resistance

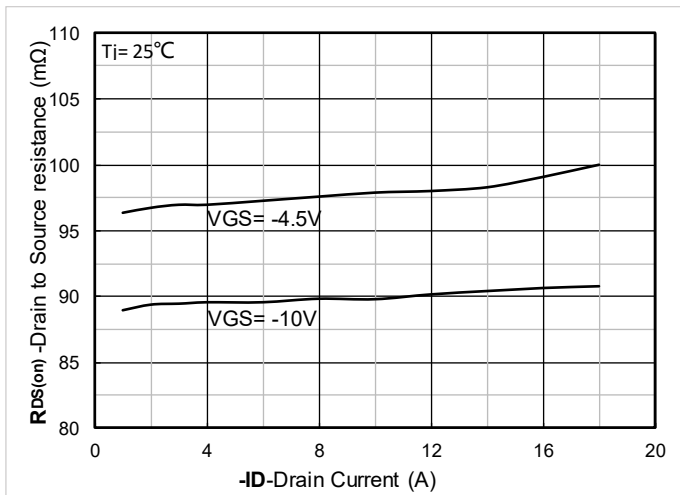


Figure 7. RDS(on) VS Drain Current

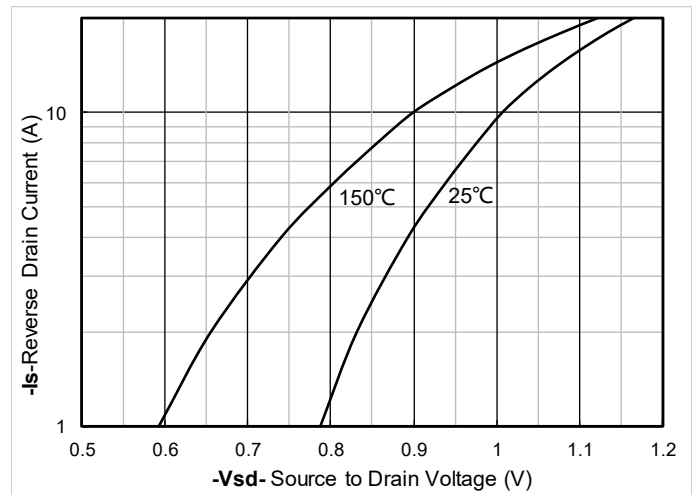


Figure 8. Forward characteristics of reverse diode

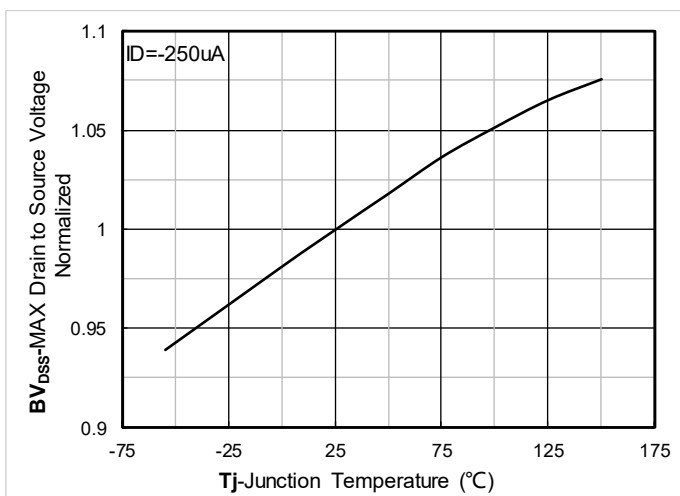


Figure 9. Normalized breakdown voltage

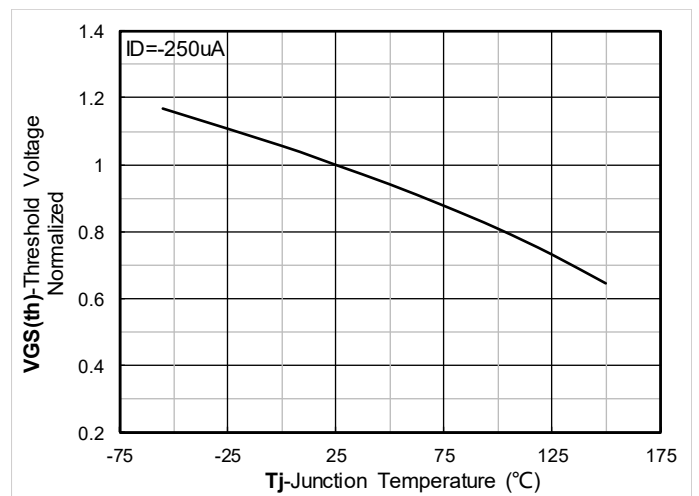


Figure 10. Normalized Threshold voltage



# YJG12NP10A

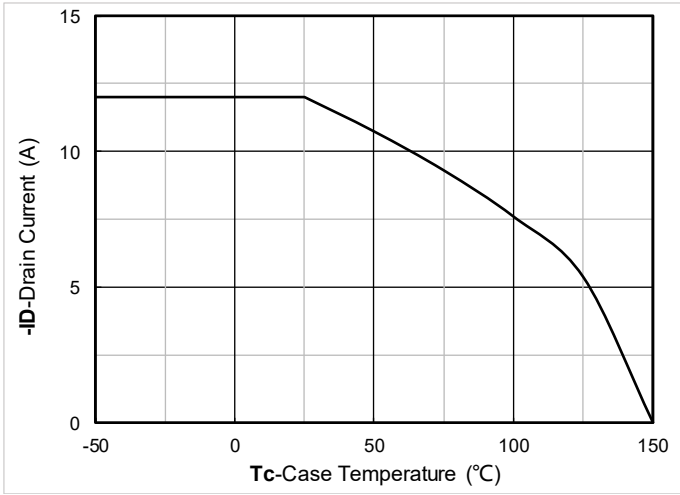
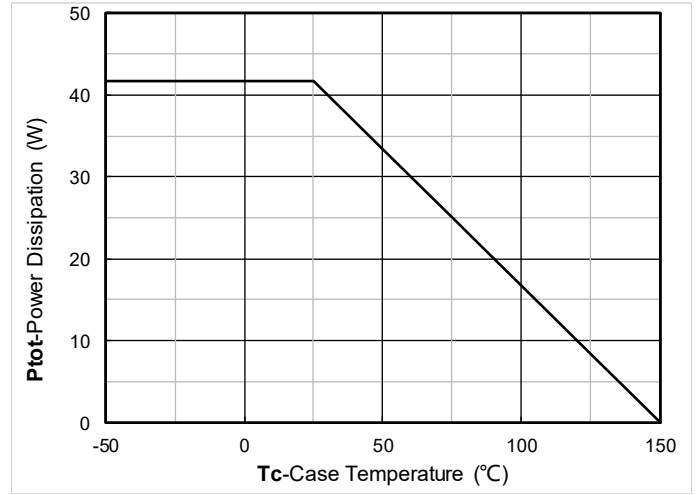


Figure 11. Current dissipation



; Figure 12. Power dissipation

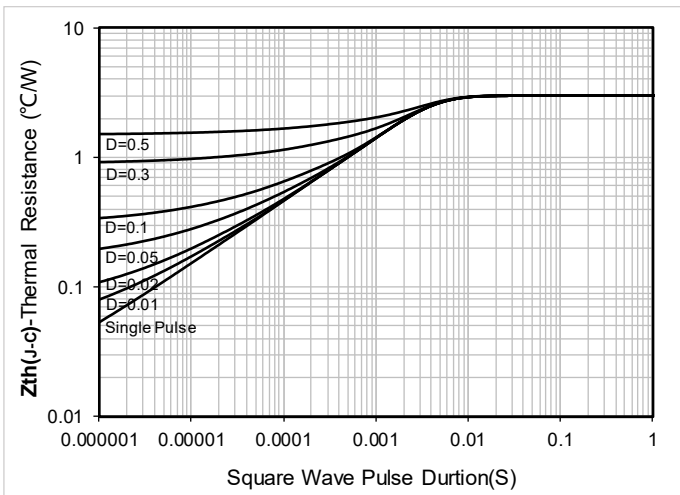


Figure 13. Maximum Transient Thermal Impedance

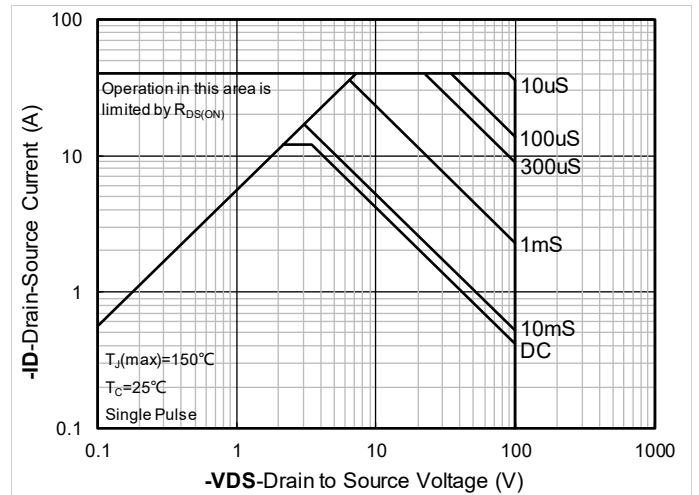


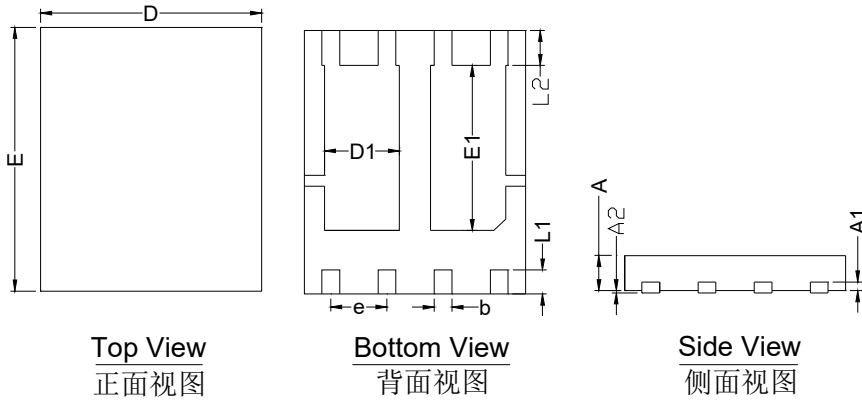
Figure 14. Safe Operation Area





# YJG12NP10A

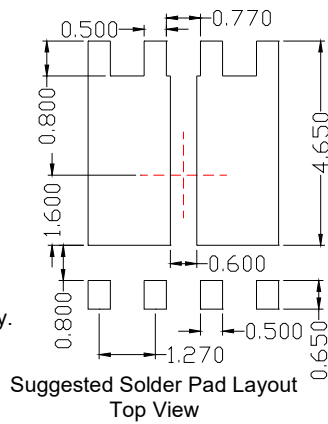
## DFN5060-8L Package information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	4.90	5.00	5.10
E	5.90	6.00	6.10
A	0.70	0.80	0.90
A1	0.20 BSC		
A2			0.10
D1	1.60	1.70	1.80
E1	3.65	3.75	3.85
L1	0.45	0.55	0.65
L2	0.80 BSC		
b	0.30	0.40	0.50
e	1.27 BSC		

**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.10\text{mm}$ .
3. The pad layout is for reference purposes only.





## YJG12NP10A

---

### Disclaimer

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website <http://www.21yangjie.com> , or consult your nearest Yangjie's sales office for further assistance.